Overview

HP Z VR Backpack G1 Workstation





Overview



Front View

- 1. Programmable RGB LED Bar
- 2. RGB LED HP logo

Overview



Top View

- 1. HTC ViveTM HMD power port
- 2. (2) USB 3.0 Type A
- 3. (1) HDMI 2.0
- 4. (1) Mini DisplayPortTM 1.3
- 5. (1) USB Type-CTM, ThunderboltTM

- 6. Audio jack
- 7. Power Button
- 8. Dock Connector
- 9. Dock Guide Posts
- 10. External Battery pow

Overview



HP Z VR Backpack G1, left side and right side view

- 1. Power Button
- 2. (2) USB 3.0 Type A
- 3. DC in port

Overview

At A Glance

- Windows 10 Pro edition
- Full performance industrial design, in a wearable form factor using a backpack harness solution. Reinforced chassis, top cover frame features customizable system health RGB LED indicator.
- Docking station solution to convert the HP Z VR Compact Workstation from backpack to desktop use modes.
- Workstation-caliber NVIDIA ® Quadro® discrete graphics: NVIDIA® Quadro® P5200 with 16GB GDDR5 memory.
- ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures.
- 7th generation Intel® CoreTM i7 with vProTM technology (vProTMoptional).
- HP Performance Advisor for optimal configuration, compatibility and performance
- Two SODIMMs, for system memory up to 32 GB.
- Supports multi-display, including up to four (4) displays, 2 direct from the HP Z VR Compact Workstation and additional 2 via docking solution.
- One (1) ThunderboltTM 3 port (supporting DisplayPortTM 1.2, USB 3.1, PCIe Gen 3 devices) on the new USB-CTM connector, for high speed data/video/audio transfer support.
- DTS Headphone:X® and DTS Studio SoundTM audio optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal clear dialog without distortion at high volume
- Internal battery to support wearable harness use mode with hot swap external batteries: 6-cell (55 WHr)
- Wireless connectivity included:
 - Intel® Dual Band Wireless-M.2/PCle AC 8265 802.11 AC/a/b/g/n (2x2) WiFi and Bluetooth® 4.2 combo adaptor (vPro)
- Dedicated storage slot: (1) M.2
- Security features including HP Client Security Manager, managed via single console.
- Designed to pass military standard Mil-Std-810G testing. MIL STD 810G testing is pending and is not intended to
 demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a
 guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any
 accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- Low halogen
- The base factory ordered HP Z VR Backpack G1 Workstation includes the following items:
 - O HP Z VR Compact Workstation
 - O HP Z VR Backpack Dock
 - O HP 330W Smart AC Adapter
 - O HP Z VR Backpack Harness
 - O 2x HP Z VR Backpack External Battery
 - O HP Z VR Backpack External Battery Charger
 - O HP 180W Smart AC Adapter
 - O HTC Vive Combo Cable

NOTE: HTC VIVE Business Edition VR System headset sold separately.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Overview

Form Factor
Operating Systems

Small Form Factor, wearable PC

Preinstalled:

Windows 10 Pro 64¹

Notes:

- Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com
- In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows® 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8 or Windows® 7 drivers on http://www.support.hp.com.

Processors*

Name	Cores	Clock Speed (GHz)	Intel® Turbo Boost Technology¹	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading
Z2 Mini G3 Performance base unit						e unit
Intel® Core i7® processor 7820HQ	4	2.9	3.9	8	2400	Y

¹The specifications shown in this column represent the maximum turbo frequency with one core active. Turbo boost stepping occurs in denoted as N/A.

NOTES:

INTEL® CoreTM i7 with vProTM

Intel® CoreTM i7 with vProTM technology is a selectable feature that is available on units configured with select processors, a qualified Intel® Centrino® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.

*Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel® CoreTM i7 with vProTM such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® CoreTM i7 with vProTM technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.



 $^{^{|2}}$ Intel HD Graphics 630 is not enabled in the HP Z VR Backpack G1. All graphics for the platform is provided by the NVIDIA® Quadro8 I

^{*} Multicore is designed to improve performance of certain software products. Not all customers or software applications will n frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is no

Overview

Graphics

Intel Integrated:

Discrete:

Video Outputs: HDMI 2.0

Mini DisplayPortTM 1.3

USB-C ThunderboltTM 3 enabled with DisplayPortTM 1.2

Intel® HD graphics 630 is NOT enabled in the HP Z VR Backpack. Disc

NVIDIA® Quadro® P5200 with 16GB dedicated GDDR5

NOTE: NVIDIA® Quadro® mobile professional graphics support up to fc (included with the HP Z VR Compact Workstation). Connecting a Virtua depending on the HMD requirements, thus reducing the number of simu

NVIDIA® GC6 Technology is supported allowing S0 state power usage

DisplayPort[™] 1.2 protocol features supported on Thunderbolt[™] 3

- Legacy displays (HDMI, DVI, VGA) may be attached to Thu
- DisplayPortTM monitors capable of supporting DisplayPort^T achieve HBR2 with the use a dongle.
- Thunderbolt[™] 3 enabled monitors may be directly attached
- DisplayPortTM1.2 MST feature ("daisy-chain" feature) is supenabled devices or DisplayPortTM1.2 monitors (requires monadongle.
- Up to 2 streams (eight lanes) of DisplayPortTM 1.2 are supple displays 24/30-bit color depth at 60 Hz or (1) 5K display supple certified ThunderboltTM cable).
- DisplayPort[™] 1.2 w/MST (Multi-stream Transport): Suppor and WUXGA (1920 x1200) monitors, 24/30-bit color depth;

ThunderboltTM 3 is superset port supporting DisplayPortTM 1.2, USB 3.1 Install all the latest drivers for your ThunderboltTM device before connect ThunderboltTM device (sold separately) must be compatible with Window Windows, see https://Thunderbolttechnology.net/products

Other System Specs

Color Black

Convertibility The HP Z VR Compact Workstation can either be placed in its docking

wearable PC for VR or AR usage.

Expansion Slots 1 80mm M.2 slot (PCle Gen3 x4)

1 30mm M.2 slot (PCIe Gen3 x1)*

* For WLAN/BT M.2 module only

Expansion Bays None

Power button, 2 USB 3.0 ports, 1 HDMI 2.0 output, 1 Mini Display Port^T

power output (for HTC ViveTM HMD, the HP HMD Combo cable provided

2 USB 3.0 ports, 330W AC Adapter DC In port

Docking connector, 2 Battery DC In ports



Top I/O

Side I/O

Bottom I/O

Overview

Chassis Dimensions Standard desktop orientation: 333.5 x 236.4 x 60.9 mm

(H x W x D)

Weight Exact weights depend upon configuration;

Minimum Weight: 2.588 kg Typical Weight: 2.588 kg

Maximum Weight: 4.658 kg* (when used as a wearable PC backpack with the Z VR Backpack harness an

Max Supported Weight (as used in backpack mode): 4.658 kg*

(2588 g (PC) + 920 g (battery x2) + 368 g (housing x2) + 782 g (Backpack)= 4658 g)

* When used as a wearable PC backpack with the Z VR Backpack harness and external batteries. Exclude

Compact Workstation.

Temperature Operating: 40° to 95°F (5° to 35°C)

Non-operating: -4° to 140°F (-20° to 60°C)

Notes: De-rate the maximum operating temperature by one degree C (1.8 degrees F) for every 305m (1,000

Humidity Operating: 8% to 85%

Non-operating: 8% to 90%

 Maximum
 Operating: 3,000 m (10,000 ft)

 Altitude
 Non-operating: 9,100 m (30,000 ft).

(non-

pressurized)

Power Supply 330W 92.6% Efficiency at 115Vac

Chipset Intel® QM 175 chipset

Memory 2 SODIMM slots, supporting up to 32GB non-ECC, DDR4 2400 MT/s

Workstation ISV See the latest list of certifications at

Certifications http://www.hp.com/united-states/campaigns/workstations/partnerships.html



Supported Components

Processors		Factory Configured	Option Kit
	7th generation Intel® Core [™] processor family Intel® Core [™] i7-7820HQ 2.9/3.9 8M 4C CPU	Υ	N

Monitors / Displays

HP DreamColor Z24x Professional Display

HP DreamColor Z27x Professional Display

HP Z34c Curved Display

HP Z22n Narrow Bezel IPS Display

HP Z23n Narrow Bezel IPS Display

HP Z24n Narrow Bezel IPS Display

HP Z24nf Narrow Bezel IPS Display

HP Z24ng Narrow Bezel IPS Display

HP Z24s IPS UHD 4K Display

HP Z25n Narrow Bezel IPS Display

HP Z27n Narrow Bezel IPS Display

HP Z27n Narrow Bezel IPS Display

Notes

HP 7 VR Backnack G1

Monitors purchased separately.

Accessories		Configured*	Option Rit	Number
	HP Z VR Backpack Harness ¹	Υ	Υ	2HY47AA
	HP Z VR Backpack Battery Pack ²	Υ	Υ	2HY48AA
	HP Z VR Backpack Battery Charger ³	Υ	Υ	2HY51AA
	HP Z VR Backpack G1 Dock ⁴	Υ	Υ	2LM71AA
	HP Z VR Backpack HTC Vive Cables ⁵	Υ	Υ	2HY49AA

^{*} All Factory Configured items listed above are mandatory DIBs (drop-in-the-box items) as part of the product base unit offering.

Factory

NOTE 1: HP Z VR Backpack Harness includes integrated carbon fiber mounting plate, two external 74Whr battery holders, and HMD parking clip.

NOTE 2: HP Z VR Backpack Battery Pack includes quantity two 74Whr external batteries.

HP 330W Smart AC Power Adapter⁶

NOTE 3: HP Z VR Backpack Battery Charger includes one 74 Whr battery charger and one 180W HP Smart AC Power Adapter.

NOTE 4: HP Z VR Backpack G1 Dock Option Kit includes the 330W HP Smart AC Power Adapter. For Factory Configured solutions, the 330W HP Smart AC Power Adapter comes with the HP Z VR Compact Workstation base unit.

NOTE 5: HTC Vive cables include custom HDMI cable, custom HTC power cable, and a custom USB 3.0 cable.



TBD

Option Kit Option Kit Par

Supported Components

NOTE 6: The HP 330W Smart AC Power Adapter is structured as part of HP Z VR Compact Workstation base unit out of the factory.

PCIe SSDs	M.2 PCle SSDs for HP Workstations	Factory Configured	Option Kit	Option Kit Pa Number
	256GB TLC	Υ	N	
	512GB TLC	Υ	N	
	1TB TLC	Υ	N	

^{**} Choice of one installed in native M.2 slot on HP Z VR Compact Workstation motherboard

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows 10) of system disk is reserved for system recovery software.

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Discrete Graphics	NVIDIA® Quadro® P5200 16GB Graphics	Υ	N		1
Notes	No CPU Integrated Graphics available	e. Only Discrete Gra	aphics enabled	d.	

Memory DDR4-2400 non-ECC Unbuffered SODIMMs

HP 16GB (2x8GB) DDR4-2400 ECC RAM HP 32GB (2x16GB) DDR4-2400 ECC RAM

NOTES: Two channels of DDR4 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

The CPUs determine the speed at which the memory is clocked. A 2400 MT/s CPU can support memory speed maximum rates of 2400 MT/s. To achieve maximum memory speed, 2400 MT/s memory must be used.

NOTE: Only unbuffered DDR4 SODIMMs are supported.

Multimedia and Audio Devices		Factory Configured	Option Kit	Option Kit Parl Number
	RealTek ALC3866-CG with Integrated DTS Headphone:X®	Υ	N	



Supported Components

Optical and Removable Storage		Factory Configured Option Ki		Option Kit Part Number
	HP SlimTray Optical Drives			
	HP External USB Optical Drive	N	Υ	F2B56AA

Actual speeds may vary. Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players. With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications		Factory Configured	Option Kit	Option Kit Par Number
	Realtek RTL8153B 10/100/1000 Mbit (no VPro)	Υ	N	
	Intel® 8265 Wireless LAN (802.11ac) and Bluetooth® 4.2 Module (with VPro TM)	Υ	N	

NOTE 1: Full Intel® vProTM Technology enabling requires the Intel 8265 Wireless LAN to be enabled and active.

NOTE 2: Realtek Ethernet access is only possible through the HP Z VR Backpack G1 Dock. Intel VPro is not supported with Realtek Ethernet.

NOTE 3: "Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Physical Security		Factory Configured	Option Kit	Option Kit Part Number
	HP Keyed Cable Lock 10mm	N	Υ	T1A62AA
	HP Master Keyed Cable Lock 10mm	N	Υ	T1A63AA
	HP Dual Head Keyed Cable Lock	N	Υ	T1A64AA
	HP Dual Head Master Cable Lock	N	Υ	T1A65AA
	HP Essential Combination Lock (Herb)	N	Υ	T0Y16AA
	HP Combination Lock (Stuart)	N	Υ	T0Y15AA



Supported Components

Input Devices		Factory Configured	Option Kit	Option Kit Parl Number
	HP Slim USB Keyboard and Mouse	N	Υ	T6T83AA
	HP Slim Wireless Keyboard and Mouse	N	Υ	T6L04AA
	HP USB Essential Keyboard and Mouse	N	Υ	H6L29AA

Other Hardware	Factory Configured	Option Kit	Option Kit Parl Number
HP Stereo 3.5mm Heads	set N	Υ	T1A66AA
HP Stereo USB Headse	t N	Υ	T1A67AA

Software		Factory Configured	Option Kit	Support Notes
	HP Performance Advisor	Υ	N	See Note 1
	HP Remote Graphics Software (RGS) 7.1	Υ	N	See Note 2
	HP Client Security Software	Υ	N	See Note 3

NOTE 1: Supports, and preinstalled with Windows 10 only. Also available as a free download from http://www.hp.com/go/performanceadvisor

NOTE 2: RGS available as a free download from http://www.hp.com/go/rgs

NOTE 3: Windows 10 OS only. HP Client Security available as a SoftPaq download.

Operating Systems Windows 10 Pro 64



System Technical Specifications

System Board

System Board Form

313 mm x 209 mm (12.3 x 8.23 inches)

Factor

Processor Socket FCBGA1440

CPU Bus Speed DMI link between CPU & PCH

Chipset Intel® QM175

Memory Expansion

Slots

2 SODIMM DDR4 memory slots

Memory Type Supported DDR4, SODIMM (Unbuffered), non-ECC

Memory Modes Non-Interleaved for single channel. Interleaved when both channels are populated.

Memory Speed

Supported

2400MHz DDR4

Memory Protection None

Maximum Memory 32GB

Memory Configuration (Supported) 8GB and 16GB non-ECC unbuffered SODIMMs are supported.

Integrated Graphics None

NOTE: Integrated Graphics is NOT enabled in the HP Z VR Backpack G1 product

Discrete Graphics NVIDIA® Quadro® P5200 with 16GB GDDR5 memory

Memory width: 256 bit

NVIDIA® CUDATM Cores: 2560

API support: DirectX 12, Shader Version 5.1, Open GL 4.5, OpenCL 1.2

Display outputs: 6 (only 4 are implemented)

DisplayPortTM 1.3

Network Controller RealTek RTL 8153B 10/100/1000 Mbs LAN. Management capabilities: WOL, PXE 2.1.

Wireless Network

Controller

M.2 PCIe Intel® 8265 WLAN/BT. Management capabilities: WOL, PXE 2.1,

vProTM/iAMT

Supported Drive

Interfaces

M.2 PCle NVMe SSD – 80mm size, 256GB, 512GB, 1TB



Display Connectors

System Technical Specifications

USB Connector(s) Top 2 USB 3.0 Type-A

1 USB 3.1 Type-CTM with ThunderboltTM 3

Side 2 USB 3.0 Type-A

Top 1 HDMI 2.0

1 mini-DisplayPortTM 1.3

1 USB 3.1 Type-CTM (DisplayPort through ThunderboltTM)

Power Connector Top 12V DC out power jack for HTC ViveTM HMD

Side DC-in power jack for external 330W power supply

Bottom DC-in integrated with dock connector

Dock Connector Bottom Proprietary combo connector that mates with the HP Z VR Backpack

Dock (HP Part Number: 2LM71AA)

HD Integrated Audio RealTek ALC3866-CG with software integration of DTS Headphone:X® and DTS Studio SoundTM

Flash ROM Yes

Chassis Fan Yes: 1 for CPU + memory + system, 1 for GPU + memory

CMOS Battery Holder Yes

- Lithium

Battery 55Whr Lithium Ion, internal

Trusted Platform

Module

Infineon SLB9670 TPM 2.0

Power Supply HeadersYes, One DC-in jack for external power supply
One 12V DC-out jack for HTC ViveTM HMD

Power Switch, Power The power and Sleep State LED are combined in the Top-Side power switch.

LED

Storage LED

Indicator

None

Clear Password

Yes

Jumper

Keyboard/Mouse Not provided with Base Unit. Separate AMO accessory.



System Technical Specifications

Power Supply 330W HP Smart AC Adapter, 92.6% efficiency, wide-ranging, active PFC Power Supply

Operating Voltage

Range

115-230 VAC

Rated Voltage Range 100-240 VAC

Rated Line Frequency 50-60 Hz

Operating Line Frequency Range

47-63 Hz

Yes

Yes

Rated Input Current

1.9A @ 90Vac

ENERGY STAR® qualified (Config

Qualified (Config Dependent)

FEMP Standby Power Yes, with Wake-on-LAN disabled: <1W in S5- Power Off

Compliant

Surge Tolerant Full

Ranging Power Supply (Common mode power surges

up to 2000V)

Internal Battery 55Whr Battery operating information shown in table below

Allowable

0 ~ 50 Charge Initial Temperature

Temperature Range 0 ~ 50 Continuous Charging

-10 ~ 60 For start of discharge below 0°C, the battery pack

must have a charge ≥ 80%

Storage Temperature

 -20 ~ 60
 1 month

 -20 ~ 45
 3 month

 -20 ~ 30
 6 month

External Battery 74Whr Battery operating information shown in table below

Allowable 0 ~ 45 Temperature Range 0 ~ 45

emperature Range 0 ~ 45 Continuous Charging

-10 ~ 60 For start of discharge below 0°C, the battery pack

must have a charge ≥ 80%

Charge Initial Temperature

Storage Temperature

-20 ~ 60 1 month -20 ~ 45 3 month -20 ~ 30 6 month



System Technical Specifications

Declared Noise Emissions

Declared Noise Emissions

System Configuration Processor Info Intel® CoreTM i7-7820HQ 2.9-3.9G/8M/4c

Memory Info 2 - 16GB DDR4-2400 SO-DIMM Memory

Graphics Info NVIDIA® Quadro® P5200 with 16GB GDDR5

Disks/SSD 1 - Samsung 1TB PCle M.2 SSD

Declared NoiseSound PowerDeskside Sound PressureEmissions (in(LWAd, bels)(LpAm, decibels)

accordance with ISO 7779 and ISO 9296)

Under Operating Load 42 42

(playing VR content)

Physical Security and Serviceability

Access Panel No access panel. Tools required to remove top cover (rubber feet covers must be removed first).

System is not designed for customer access.

Hard Drives None

Expansion Cards M.2 module requires a screwdriver to service and replace.

Processor Socket No CPU socket. CPU soldered on motherboard.

Memory Tool-less. Must remove shielding cover (for EMI) first (requires tools).

System Board Screw-In

Single Color Power and The Power LED is on the front of the system. No HDD LED on the system.

HD LED on Front of

Computer

Over-Temp Warning on No. System will automatically throttle in over-temperature situations.

Screen

Restore CD/DVD Set None

Dual Function Front

Power Switch

Yes, causes a fail-safe power off when held for 4 seconds (default)

Cable Lock Support Yes, but requires use of the HP Z VR Backpack Dock with a Kensington Cable Lock solution

(optional): Locks HP Z VR Compact Workstation to the Dock once cable lock is engaged on the



System Technical Specifications

docking station. Secures HP Z VR Compact Workstation to docking station.

3 mm x 7 mm slot on the HP Z VR Backpack Dock station.

Serial, Parallel, **Enable/Disable Port** Control

No serial or parallel ports are available on the HP Z VR Compact Workstation.

USB Enable/Disable Port Control

Yes - enable/disable per port control.

Removable Media Write/Boot Control

Yes, prevents ability to boot from removable media on supported devices (and can disable writes

to media)

Power-On Password

Yes, prevents an unauthorized person from booting up the workstation

Setup Password

Yes, prevents an unauthorized person from changing the workstation configuration

NIC LEDs (integrated) (Green & Amber)

No. RJ45 NIC port is on the HP Z VR Backpack Dock only

CPUs and Heatsinks

Not serviceable.

Power Supply Diagnostic LED No. Not applicable.

Front Power LED

Yes, white

Internal Speaker

No

System/Emergency **ROM Flash Recovery** Crisis recovery feature recovers from corrupted system BIOS by using Boot Block support.

Cooling Solution

Air cooled forced convection

CPU Heatsink Fan

Yes. Heatsink is common between CPU and GPU assembly areas.

GPU Heatsink Fan

Yes. Heatsink is common between CPU and GPU assembly areas.

Chassis Fan

Two fan system.

Memory Heatsink Fan

No

HP PC Hardware Diagnostics UEFI HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available

as a download from HP Support.

Access Panel Key Lock Not applicable. No chassis access panel.



ACPI-Ready Hardware

Advanced Configuration and Power Management Interface (ACPI).

- Allows the system to wake from a low power mode.
- Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Chip

Yes

M.2 Card Retention

Yes, all M.2 modules are retained by a single screw

Flash ROM

Yes

DIMM Connectors

Yes, 2 SODIMM connectors

BIOS

PCI 3.0 Support

Full BIOS support for PCI Express through industry standard interfaces.

BBS

BIOS Boot Specification v1.01.

Provides more control over how and from what devices the workstation will boot.

WMI Support

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM Flash Recovery with Video Recovers system BIOS in corrupted Flash ROM.

Replicated Setup

Saves BIOS settings to USB flash device in human readable file. BIOS Configuration Utility (BCU) utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).

SMBIOS

System Management BIOS 2.8., for system management information.

Boot Control

Disables the ability to boot from removable media on supported devices.

Thermal Alert

Monitors the temperature state within the chassis. Three modes:

- NORMAL normal temperature ranges.
- ALERTED excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown.
- SHUTDOWN excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs.



Remote ROM Flash

Provides secure, fail-safe ROM image management from a central network console.

Updates can be performed before starting the OS.

Updates can be periodically scheduled.

ACPI (Advanced Configuration and Power Management Interface) Allows the system to enter and resume from low power modes (sleep states).

Enables an operating system to control system power consumption based on the dynamic

workload.

Makes it possible to place individual cards and peripherals in a low-power or powered-off state

without affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Remote Wakeup/Remote Shutdown System administrators can power on, restart, and power off a client computer from a remote

location.

ASF 2.0 Compliant

Yes.

Instantly Available PC (Suspend to RAM - ACPI sleep state S3)

Allows for very low power consumption with quick resume time.

Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server) Allows a new or existing system to boot over the network and download software, including the

operating system.

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS) so that management SW applications

can use and report this information.

System board revision

level

Allows management SW to read revision level of the system board.

Revision level is digitally encoded into the HW and cannot be modified.

Start-up Diagnostics (Power-on Self-Test)

Assesses system health at boot time with selectable levels of testing.

Auto Setup when new hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation

The system can be booted without a keyboard.

Localized ROM Setup

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 5 languages

with local keyboard mappings.

Asset TagThe user or IT administrator to set a unique tag string in non-volatile memory.

Per-slot Control Allows I/O slot parameters (option ROM enable/disable) to be configured individually.



Adaptive Cooling Control parameters are set according to detected hardware configuration for optimal acoustics.

Pre-boot Diagnostics (Pre-video) critical errors are reported via beeps and blinks on the power LED.

Digitally and Cryptographically Signed BIOS Helps to prevent the installation of unauthorized versions of a BIOS (a rogue BIOS) from a virus, malware, or other code that could lead to compromised system security, data access, physical service, or even system board replacement.

Boot Block Emergency Recovery Mode (BIOS Recovery) The HP BIOS offers a write-protected boot block ROM that provides recovery from a failed flashing of the computer BIOS. This special recovery mode prevents the system from becoming unusable or "bricked" when a BIOS update is interrupted.

UEFI Specification Revision

UEFI 2.5.0

ACPI Advanced Configuration and Power Management Interface, Version 6.0

ASF Alert Standard Format Specification, Version 2.0

EDD - Enhanced Disk Drive Specification Version 1.1

- BIOS Enhanced Disk Drive Specification Version 3.0

PCI Express PCI Express Base Specification, Revision 3.0.

PMM POST Memory Manager Specification, Version 1.01

SATA - Serial ATA Specification, Revision 1.0a

Serial ATA II: Extensions to Serial ATA 1.0, Revision 1.0a
 Serial ATA II Cables and Connectors Volume 2 Gold

- SATA-IO SATA Revision 3.0 Specification

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

TPM Trusted Computing Group TPM Specification Version 2.0

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.0 Specification

Social and Environmental Responsibility

Eco-Label Certifications This product is low halogen except for power cords, cables and peripherals. Service parts obtained after purchase may not be Low Halogen.

- ENERGY STAR® (energy-saving features available on selected configurations –Windows® only)
- US Federal Energy Management Program (FEMP)China Energy Conservation Program (CECP)
- IT FCO dealeration

IT ECO declaration

Batteries The battery in this product complies with EU Directive 2006/66/EC



Battery size: CR2032 (coin cell) Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

Batteries - Internal 55Whr

The battery in this product complies with EU Directive 2006/66/EC

Battery size: 6 cell

Battery type: Lithium ion Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

Lead greater than 40ppm by weight

Restricted Material Usage

This product meets the material restrictions specified in HP's General Specification for the Environment. http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf

HP Inc. is committed to compliance with all applicable environmental laws and regulations. including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis.

Low Halogen Statement This product is low halogen except for power cords, cables and peripherals. Service parts obtained after purchase may not be Low Halogen.

and Recycling

End-of-Life Management HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Living Progress Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

Additional Information

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product is >90% recycle-able when properly disposed of at end of life
- EPEAT® Silver registered in the U.S. EPEAT registration varies by country. See http://www.epeat.net for registration status by country.

Packaging

HP Workstation product packaging meets the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/society/gen specifications.html

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed



- Maximizes the use of post-consumer recycled content materials in packaging materials
- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting

Packaging Materials Internal

Cushions made from fabricated recycled expanded-polyethylene (EPE) or recycled expanded-polypropylene (EPP). May also be made from recycled molded paper-pulp (MPP). Carton made from corrugated fiberboard with at least 25% recycled content.

Manageability

Intel® Active The HP Z VR Compact Workstation supports Intel® vProTM technology when purchased with a vProTM Management technology capable CPU: Intel® CoreTM i7 processors with Intel® VT-d/VT-x and Intel® TXT technology. Technology

(AMT)

External

Remote Visit: http://www.hp.com/go/easydeploy

Manageability Software Solutions

System Visit: http://www.hp.com/go/ssm

Software Manager Service,

Limited 1-year limited warranty. Batteries have a default one year limited warranty.

Support, and Warranty

Optional HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc. Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



Technical Specifications - Processors

Name	Cores	Clock Speed (GHz)	Intel® Turbo Boost Technology¹	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Integrated Graphics	Featuring Intel® vPro TM Technology	TDP (W)
Z2 Mini G3 Performance base unit									
Intel® Core i7® processor 7820HQ	4	2.9	3.9	8	2400	Y	Intel® HD Graphics 630 ²	Y	45W

The specifications shown in this column represent the maximum turbo frequency with one core active. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A.

Intel HD Graphics630 is not enabled in the HP Z VR Backpack G1. All graphics for the platform is provided by the NVIDIA Quadro



P5200 GPU.

Technical Specifications - Storage

M.2 NVMe SSD 1TB TLC Capacity 1024GB

Protocol NVMe
Form Factor M.2 2280
Controller NVMe
Rated for 24/7/365 NO

operation

Physical Size (Height) 0.14 in; 3.65 mm
Physical Size (Width) 0.87 in; 22 mm

Drive Weight 0.02; 10 g

Interface PCle NVMe Gen3 x4

Synchronous Transfer Read: Up to 3300 MB/s; Write: Up to 1,775

Rate (Maximum) MB/s

Operating Temperature 32° to 158° F (0° to 70° C)

M.2 NVMe SSD 512GB TLC Capacity 512GB

Protocol NVMe
Form Factor M.2 2280
Controller NVMe
Rated for 24/7/365 NO

operation

Physical Size (Height) 0.14 in; 3.65 mm
Physical Size (Width) 0.87 in; 22 mm
Drive Weight 0.02; 10 g

Interface PCle NVMe Gen3 x4

Synchronous Transfer Read: Up to 3200 MB/s; Write: Up to 1300

Rate (Maximum) MB/s

Operating Temperature 32° to 158° F (0° to 70° C)

M.2 NVMe SSD 256GB TLC Capacity 256GB

Protocol NVMe
Form Factor M.2 2280
Controller NVMe
Rated for 24/7/365 NO

operation

Physical Size (Height) 0.14 in; 3.65 mm
Physical Size (Width) 0.87 in; 22 mm
Drive Weight 0.02; 10 g

Interface PCIe NVMe Gen3 x4

Synchronous Transfer Read: Up to 3200 MB/s; Write: Up to 1255

Rate (Maximum) MB/s

Operating Temperature 32° to 158° F (0° to 70° C)

Technical Specifications - Graphics

NVIDIA® Quadro® P5200 16GB Graphics

Maximum Resolution DisplayPort 1.3:

- up to 4096x2160 x 30 bpp @ 60Hz

- supports High Bit Rate 2 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 output:

- up to 4096x2160 x 30 bpp @ 60Hz

Image Quality Features Stereoscopic 3D display support including NVIDIA® 3D VisionTM

technology, 3D DLP, Interleaved, and passive stereo

Display Output Maximum number of displays:

- 4 direct attached monitors

Maximum number of DisplayPortTM displays possible per DisplayPortTM output (Multiple displays daisy-chained from one DisplayPortTM 1.3 port requires DisplayPortTM 1.2 MST capable displays or DP1.3 MST

capable hub):

- 4 1920x1200 @ 60 Hz - 2 2560x1600 @ 60 Hz - 1 4096x2160 @ 60 Hz

Maximum number of monitors across all available Quadro P5200

outputs is 4.

Supported Graphics

APIs

OpenGL 4.5 DirectX 12

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python, and

Fortran

Available Graphics Drivers

Microsoft Windows 10

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Network

Realtek RTL8153B GbE Controller Connector RJ-45

Controller Realtek RTL8153B GbE platform LAN connect networking controller,

USB 3.0 bus connection to host.

Memory Tx and Rx packet buffer memory

Data Rates Supported 10/100/1000 Mbps

Compliance 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i,

802.3u

Bus Architecture USB 3.0

Data Transfer Mode USB-based interface for active state operation (S0 state) and SMBus

for host and management traffic (Sx low power state)

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex (not supported for the 1000BASE-T

transceiver)

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Management Capabilities

WOL, auto MDI crossover, PXE, RSS, ACPI, Advanced cable

diagnostic, loopback modes, LPM, VLAN, Multicast Listener Discovery

(MLD)

Intel® 8265 Wireless LAN (802.11ac) and Bluetooth 4.2 Module **Connector** M.2 (Supports 2230 form factor; E Key) Motherboard Interface

Controller Intel® Dual Band Wireless-AC 8265

Compliance Wireless LAN: IEEE 802.11abgn, 802.11ac, 802.11d, 802.11e,

802.11i, 802.11h, 802.11w, WMM, WMM-PS, WPA, WPA2, WPS2,

Protected Management Frames

FIPS, FISMA

Bluetooth®: Dual Mode Bluetooth® 2.1, 2.1+EDR, 3.0, 4.0, BLE, and

4.2

Antenna 2x2 Tx/Rx Streams 2x2

Bands 2.4 GHz, 5GHz

Bus Architecture PCI Express Gen3 x1 and USB 2.0

Management Capabilities

Wake on WLAN (in all sleep states, excluding Max Power Savings mode), WFA Management Frame Protection (802.11w), F10 BIOS

Menu option to disable/enable WLAN and Bluetooth® radios, supports

seamless roaming between 802.11 wireless access points

Throughput Max PHY throughput 867 Mbps (802.11ac) for WLAN



Technical Specifications - Network

Notes

Wireless access point and internet service required. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.



Technical Specifications - Power

HP 330W Smart AC Adapter (for HP Z VR Compact Workstation) **Dimensions** 5.9 x 5.9 x 1.48 in (150 x 150 x 37.5 mm)

Weight 2.43lb / 1.1kg nominal Input 100 to 240 VAC

Input Efficiency 92.6% average at 115Vac and 93.2%

average at 230Vac

Input frequency range 47 to 63 Hz

Input AC current 4.2A RMS at 90 VAC, maximum

Output Output power 330W nominal

DC output 19.5 VDC nominal

Hold-up time 10 msec at 115 VAC input with maximum

load

Output current limit 34A (5ms)

Over voltage protection Shall not exceed 29 Volts for no longer than

250ms, auto shutdown

Connector 3 pin/grounded, mates with interchangeable cords **Environmental Design** Operating 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

Altitude Up to 16400 ft (5000 m)

Humidity up to 95%, non-condensing

Storage Humidity up to 95%, non-condensing

EMI and Safety Certifications

CE Mark- full compliance with LVD and EMC directives; Worldwide safety standards- IEC950, EN60950, UL1950, Class 1, SELV; Agency approvals- C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class B, CISPR22 Class B, CCIB, NOM-1 NYCE; MTBF- over 200,000 hours

at 25°C ambient condition.

HP 180W Smart AC Adapter (for external battery charger)

Dimensions 7.1 x 3.35 x 1.65 in (180 x 85 x 42mm)

 Weight
 1.81 lb (820 g)

 Input
 90 to 264 VAC

Input Efficiency 89% min at 115 VAC

Input frequency range 47 to 63 Hz

Input AC current 2.5 A at 90 VAC, 1.45 A at 180 VAC

Output Output power 180W nominal

DC output 19.5V nominal

Hold-up time >5 msec at 115 VAC input

Output current limit Not exceed 240VA for more than 60s,

automatic shutdown

Over voltage protection 29V max for no longer than 250ms,

automatic shutdown

Connector 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating



Technical Specifications - Power

temperature 41° to 95° F (5° to 35° C)

Non-operating (storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16405 ft (0 to 5000 m) with 32° C max

ambient temperature at max altitude

Humidity 20% to 95%

EMI and Safety Certifications

Worldwide safety and EMC approvals including CE, UL, CSA or cUL, GS, Australian Electric Permit, C-tick, NOM, CCC, KC, GOST, SABS, S

mark, BSMI, ISC, PSE, PSB and SII.



Option Type	Description	Part Number
HP Z VR Backpack	HP Z VR Backpack Harness HP Z VR Backpack Battery Pack HP Z VR Backpack Battery Charger HP Z VR Backpack HTC Vive Combo Cable HP Z VR Backpack G1 Dock	2HY47AA 2HY48AA 2HY51AA 2HY49AA 2LM71AA
Input/Output	HP Slim USB Keyboard and Mouse HP Slim Wireless Keyboard and Mouse HP USB Essential Keyboard and Mouse HP Stereo 3.5mm Headset HP Stereo USB Headset USB-C to HDMI 1.4 HP USB-C to DisplayPort Adapter	T6T83AA T6L04AA H6L29AA T1A66AA T1A67AA N9K77AA N9K78AA
Power	HP 180W AC adapter HP 330W Smart AC Adapter	TBD TBD
Security	HP Essential Combination Lock (Herb) HP Combination Lock (Stuart) HP Dual Head Keyed Cable Lock (Sumo) HP Dual Head Master Cable Lock (Sumo MK) HP Keyed Cable Lock 10mm HP Master Keyed Cable Lock	T0Y16AA T0Y15AA T1A64AA T1A65AA T1A62AA T1A63AA
Storago ovtornal	UD External LISP Ontical Drive	F2B56AA
Storage - external	HP External USB Optical Drive	FZBOOAA



Summary of Changes

Date of change:	Version History:	Description of change:			
	From v1 to v2				



title

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